

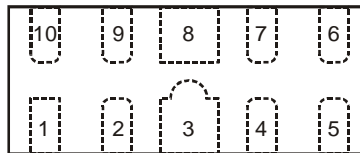
**4 CHANNEL LOW CAPACITANCE TVS DIODE ARRAY**
**Features**

- Clamping Voltage: 9V at 10A 100ns TLP; 9V at 6A 8 $\mu$ s/20 $\mu$ s
- IEC 61000-4-2 (ESD): Air – +20/-18kV, Contact – +20/-16kV
- IEC 61000-4-5 (Lightning):  $\pm$ 6A (8/20 $\mu$ s)
- 4 Channels of ESD Protection
- Low Channel Input Capacitance of 0.5pF Typical
- TLP Dynamic Resistance: 0.25 $\Omega$
- Typically Used for High Speed Ports Such as USB 2.0, DVI™, HDMI™, Ethernet Port, IEEE, MDDI, PCI Express®, SATA/ eSATA
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. “Green” Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**

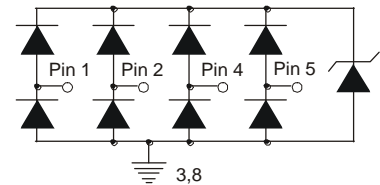
**Mechanical Data**

- Case: U-DFN2510-10
- Case Material: Molded Plastic, “Green” Molding Compound; UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: NiPdAu over Copper Leadframe (Lead-Free Plating) Solderable per MIL-STD-202, Method 208 **(e4)**
- Weight: 0.038 grams (Approximate)

Pin #	Description
1, 2, 4, 5	I/O
6, 7, 9, 10	No Connection
3, 8	V <sub>SS</sub>



Pin Description (Top View)



Device Schematic

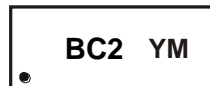
**Ordering Information (Note 4)**

Part Number	Compliance	Marking	Reel Size (inches)	Tape Width (mm)	Quantity per Reel
DT1140-04LP-7	AEC-Q101	BC2	7	8	3,000/Tape & Reel

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
  2. See <https://www.diodes.com/quality/lead-free/> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
  3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
  4. For packaging details, go to our website at <https://www.diodes.com/design/support/packaging/diodes-packaging/>.

**Marking Information**

U-DFN2510-10



BC2 = Product Type Marking Code  
 YM = Date Code Marking  
 Y = Year (ex: F = 2018)  
 M = Month (ex: 9 = September)

## Date Code Key

Year	2013	2014	2015	2016	2017	2018
Code	A	B	C	D	E	F

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

**Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	Conditions
Peak Pulse Current, per IEC 61000-4-5	I <sub>PP</sub>	6	A	I/O to V <sub>SS</sub> , 8/20μs
Peak Pulse Power, per IEC 61000-4-5	P <sub>PP</sub>	60	W	I/O to V <sub>SS</sub> , 8/20μs
Operating Voltage (DC)	V <sub>DC</sub>	6	V	I/O to V <sub>SS</sub>
ESD Protection – Contact Discharge, per IEC 61000-4-2	V <sub>ESD_CONTACT</sub>	+20/-16	kV	I/O to V <sub>SS</sub>
ESD Protection – Air Discharge, per IEC 61000-4-2	V <sub>ESD_AIR</sub>	+20/-18	kV	I/O to V <sub>SS</sub>
Operating Temperature	T <sub>OP</sub>	-55 to +85	°C	—
Storage Temperature	T <sub>STG</sub>	-55 to +150	°C	—

**Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Power Dissipation Typical (Note 5)	P <sub>D</sub>	350	mW
Thermal Resistance, Junction to Ambient Typical (Note 5)	R <sub>θJA</sub>	360	°C/W

**Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Conditions
Reverse Working Voltage	V <sub>RWM</sub>	—	—	5.5	V	I <sub>R</sub> =1mA, I/O to V <sub>SS</sub>
Reverse Current (Note 6)	I <sub>R</sub>	—	—	50	nA	V <sub>R</sub> = 5V, I/O to V <sub>SS</sub>
Reverse Breakdown Voltage	V <sub>BR</sub>	6	—	—	V	I <sub>R</sub> = 1mA, I/O to V <sub>SS</sub>
Forward Clamping Voltage	V <sub>F</sub>	-1.0	-0.85	—	V	I <sub>F</sub> = -15mA, I/O to V <sub>SS</sub>
Holding Voltage	V <sub>H</sub>	5.5	—	—	V	—
Reverse Clamping Voltage (Note 7)	V <sub>C</sub>	—	6.4	—	V	I <sub>PP</sub> = 1A, I/O to V <sub>SS</sub> , 8/20μs
Reverse Clamping Voltage (Note 7)	V <sub>C</sub>	—	9	10	V	I <sub>PP</sub> = 6A, I/O to V <sub>SS</sub> , 8/20μs
Trigger Voltage	V <sub>TRIG</sub>	—	—	9.5	V	—
ESD Clamping Voltage	V <sub>ESD</sub>	—	9	—	V	TLP, 10A, t <sub>p</sub> = 100ns, I/O to V <sub>SS</sub>
Dynamic Reverse Resistance	R <sub>DIF-R</sub>	—	0.25	—	Ω	TLP, 10A, t <sub>p</sub> = 100ns, I/O to V <sub>SS</sub>
Dynamic Forward Resistance	R <sub>DIF-F</sub>	—	0.25	—	Ω	TLP, 10A, t <sub>p</sub> = 100ns, V <sub>SS</sub> to I/O
Channel Input Capacitance	C <sub>I/O</sub>	—	0.5	0.65	pF	V <sub>I/O</sub> = 2.5V, V <sub>SS</sub> = 0V, f = 1MHz

- Notes:
- Device mounted on FR-4 PCB pad layout (2oz copper) as shown on Diodes Incorporated's suggested pad layout, which can be found on our website at <http://www.diodes.com/package-outlines.html>.
  - Short duration pulse test used to minimize self-heating effect.
  - Clamping voltage value is based on an 8x20μs peak pulse current (I<sub>pp</sub>) waveform.

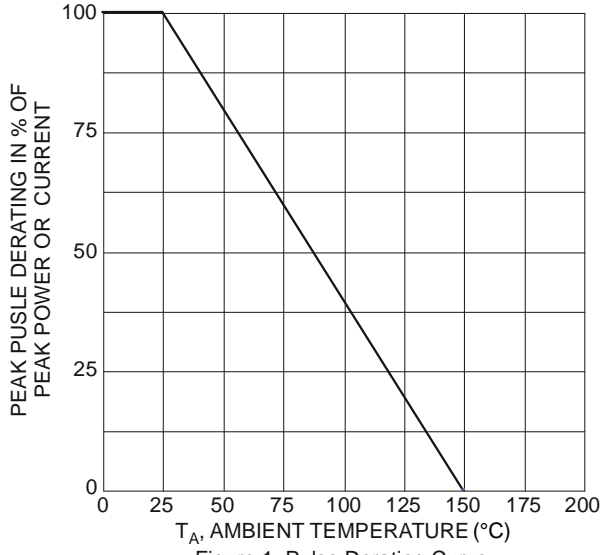


Figure 1 Pulse Derating Curve

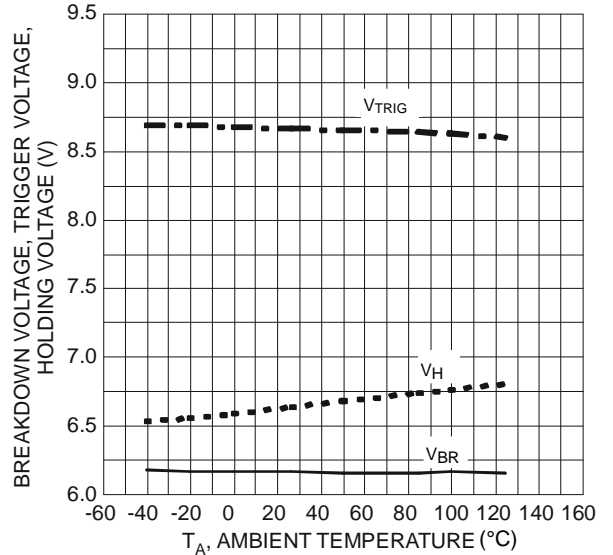


Figure 2 BV, Trigger Voltage, Holding Voltage vs. Ambient Temperature

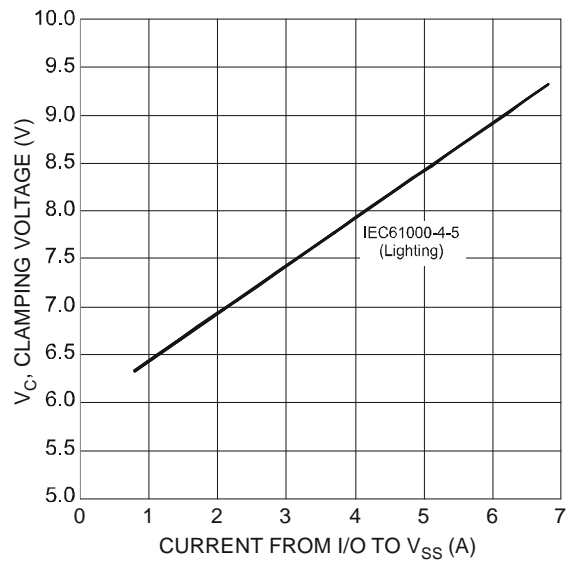


Figure 3 Clamping Voltage Characteristic

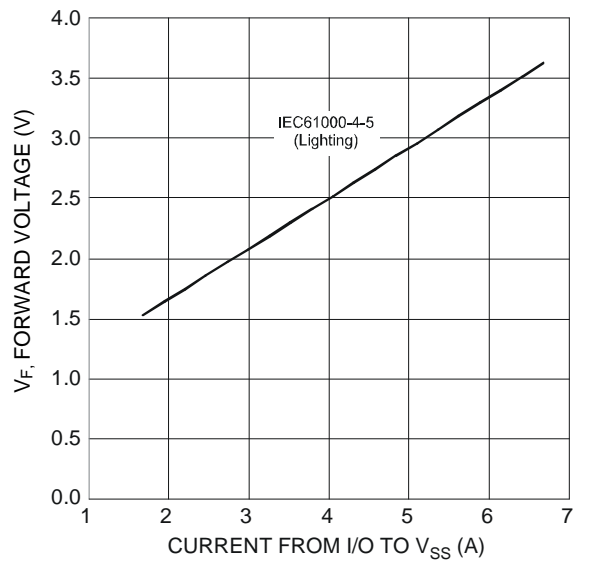


Figure 4 Forward Voltage Characteristic

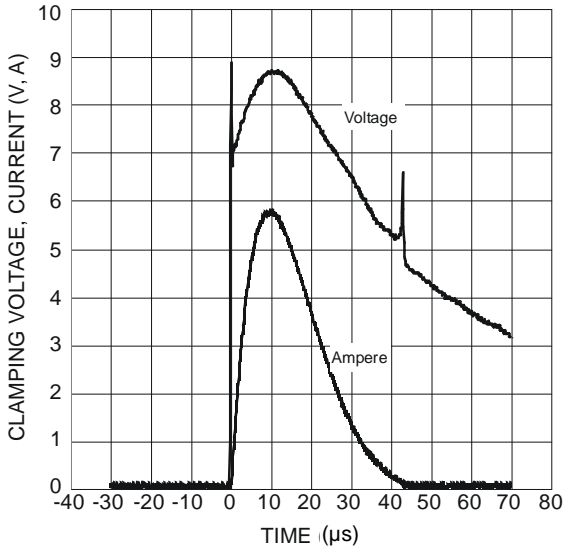


Figure 5 Waveform of Clamping Voltage, Current vs. Time (8/20µs, I/O to V<sub>SS</sub>)

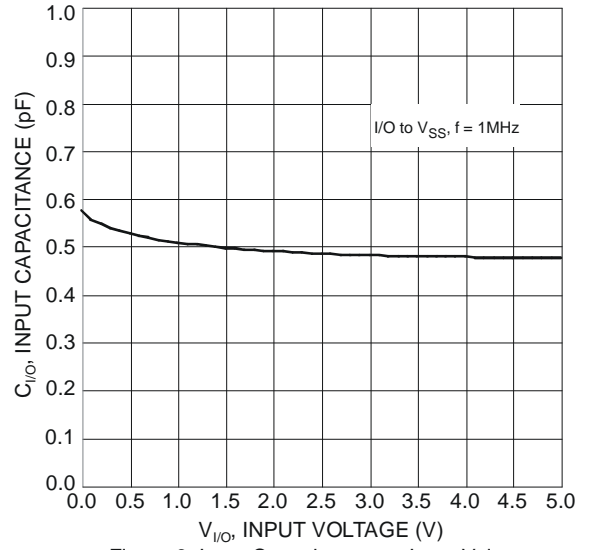


Figure 6 Input Capacitance vs. Input Voltage

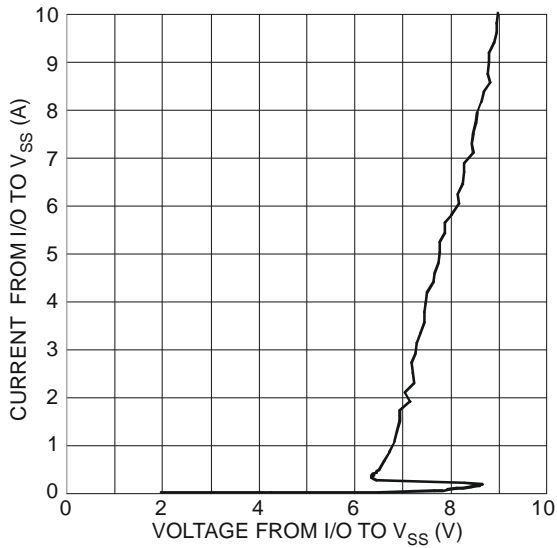
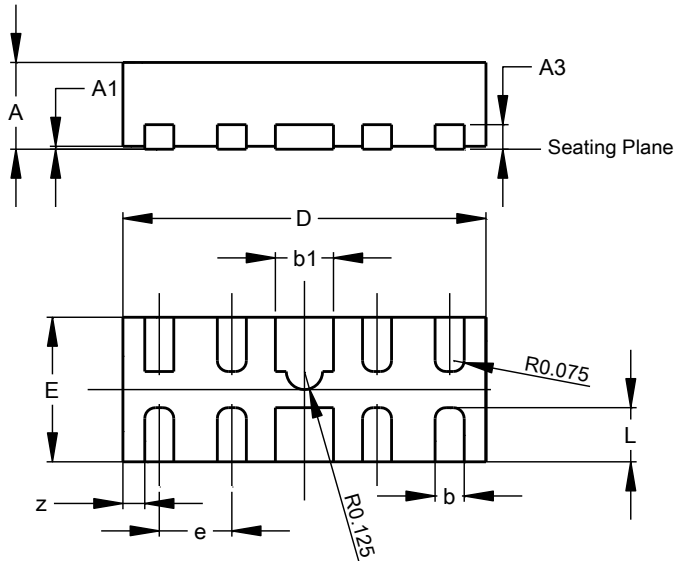


Figure 7 Current vs. Voltage

## Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

U-DFN2510-10

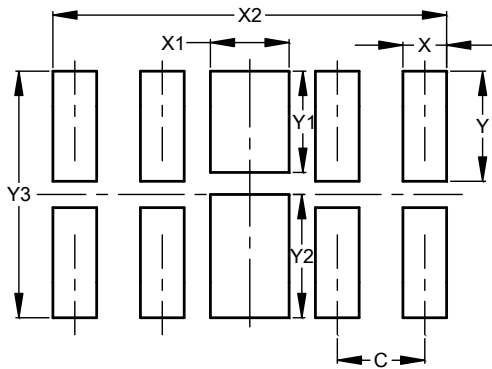


U-DFN2510-10			
Dim	Min	Max	Typ
A	0.545	0.605	0.575
A1	0.00	0.05	0.03
A3	-	-	0.13
b	0.15	0.25	0.20
b1	0.35	0.45	0.40
D	2.450	2.575	2.500
e	-	-	0.50
E	0.950	1.075	1.000
L	0.325	0.425	0.375
z	-	-	0.150
All Dimensions in mm			

## Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

U-DFN2510-10



Dimensions	Value (in mm)
C	0.500
X	0.250
X1	0.450
X2	2.250
Y	0.625
Y1	0.575
Y2	0.700
Y3	1.400

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